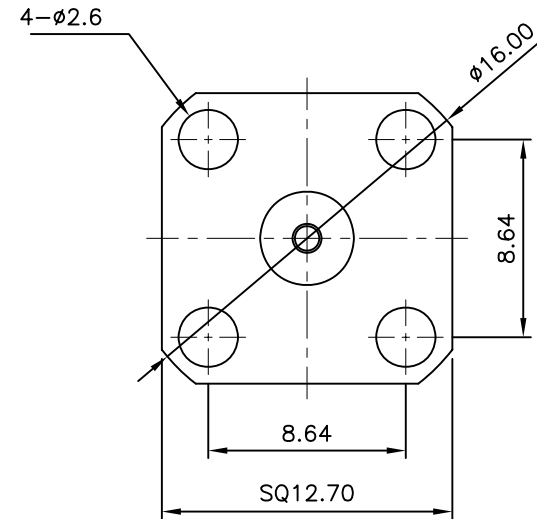
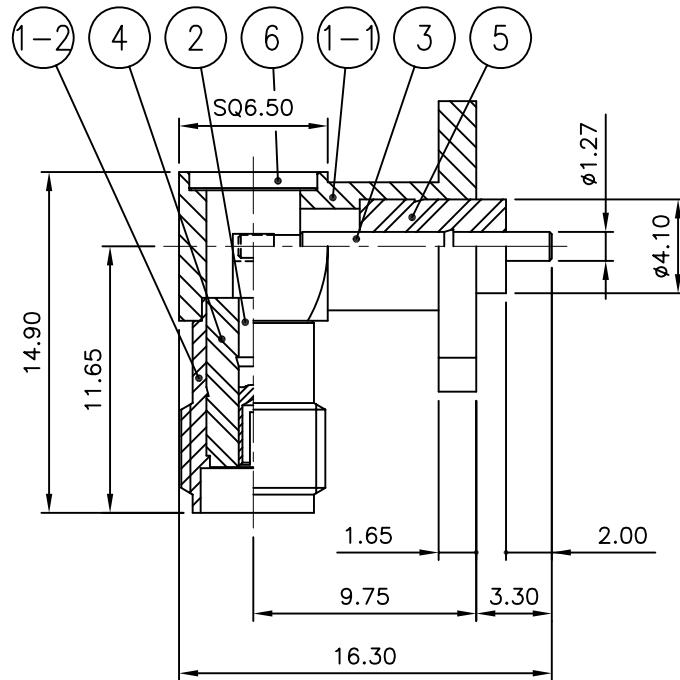


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1R	Initial Registration	S.M.LEE	I.C.KIM	2014.09.18.



6	COVER	1	MBsBD	SUCO 3.0μm min.	DCV00038-5/2
5	INSULATOR	1	TEFLON		DIN02436-N/1
4	INSULATOR	1	TEFLON		DIN01893-N/1
3	CONTACT	1	MBsBD	Silver 3.0μm min.	DCT03207-5/1
2	CONTACT	1	BeCu	Silver 3.0μm min.	DCT02428-5/2
1	1-2 BODY	1	MBsBD	SUCO 3.0μm min.	DBD02901-3/1
	1-1 BODY	1	MBsBD	SUCO 3.0μm min.	DBD03591-1/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2014. 09. 18.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL	_____	CHECKED BY		TITLE SMA50 SOLDER END JL-4H
		DRAWN BY	S.M.LEE	
FINISH	_____	SCALE	UNIT	DWG NO. CN03185-7/2 REVISION I R SHEET 1 of 1
		3/1	mm	